IPC  ASSOCIATION CON ELECTRONICS IND	Material Comp © Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
upplier In	nformation						·								
Company name* Company				unique ID			Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name	e	Title - Contac	Title - Contact			Phone - Contact*				Email - Contact*					
Product-Env-	-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorized Re	epresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
roduct-Env-	-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Re	equester Item Number	Mfr Item	n Number	Mfr Item Name			Effective Date Version Manufacturing Si		g Site	V	/eight*	UOM	Unit Type		
		LC87F0808AUQFPTL 8-bit Microcontroller M-H		ller		2023-06-08	3			2	0.00	mg	Each		
Ianufactu	ring Proccess Informa	ntion													
Terminal Plating / Grid Array Material Te			Perminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperatur		ıre Max Time	at Peak	Temperatu	re Num	ber of Reflow Cyc	eles		
contains Bi		CU Alloy 3		3		<b>260</b> C		30	seco		s <b>3</b>				
omments															
<b>ITENTION</b>	: MSL 3 Rated item require	es Bake and D	Ory Pack (after	electrical test)											
or more info	rmation regarding material	composition	please refer to	page 3					·					·	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.72	mg	Supplier	Silicon (Si)	7440-21-3		2.7031	mg
			Supplier	Polyimide	Proprietary Data		0.0169	mg
Die Attach	0.26	mg	Supplier	Silver (Ag)	7440-22-4		0.1989	mg
			Supplier	Epoxy resins	129915-35-1		0.0611	mg
Lead Frame	89.69	mg	Supplier	Silver (Ag)	7440-22-4		0.4664	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0807	mg
			Supplier	Manganese (Mn)	7439-96-5		0.7086	mg
			Supplier	Silicon (Si)	7440-21-3		0.2601	mg
			В	Nickel (Ni)	7440-02-0		37.024	mg
			Supplier	Iron (Fe)	7439-89-6		51.1412	mg
			Supplier	Phosphorus (P)	7723-14-0		0.009	mg
Mold Compound-Black	105.48	mg		Epoxy Phenol Resin	proprietary data		14.7672	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5274	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		89.658	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5274	mg
Plating	1.43	mg	В	Bismuth (Bi)	7440-69-9		0.0086	mg
			Supplier	Tin (Sn)	7440-31-5		1.4214	mg
Wire Bond - Au	0.42	mg	Supplier	Gold (Au)	7440-57-5		0.42	mg